



[Home](#) > [Products](#) > [Memory](#) > [Nonvolatile Products](#) > [nvSRAM Serial](#) > [CY14ME064Q2A-SXIT](#)

CY14ME064Q2A-SXIT Status: In Production

 [Alert me about changes to this product](#)

 [SHARE](#)   

[Datasheet](#)

[Quality and RoHS](#)

[Support and Community](#)

[Inventory](#)

[Technical Documents](#)

[Packaging/Ordering](#)

[Related Products](#)



CY14ME064Q2A-SXIT

Automotive Qualified	N
Min. Operating Voltage (V)	4.50
Max. Operating Voltage (V)	5.50
Min. Operating Temp. (°C)	-40
Max. Operating Temp. (°C)	85
Frequency (MHz)	40
Temp. Classification	Industrial
Max. Operating VCCQ (V)	3.60
Min. Operating VCCQ (V)	2.70
Speed (ns)	N/A
Density (Kb)	64
Organization (X x Y)	SPI

Pricing & Inventory Availability

1-10 unit Price*	11-100 unit Price*	101-1000 unit Price*	1001 + unit Price*

Availability	Quantity	Ships In	Order Now

* Prices are shown in United States dollars and are for budgetary use only.

Packaging / Ordering

Package	SOIC
No. of Pins	8
Package Dimensions	193 L X 1.46 H X 150 W (Mils)
Package Weight	76.45 (mgs)
Package Cross Section Drawing	Download
Package Carrier	REEL
Package Carrier Drawing / Orientation	Tape Drawing , Reel Drawing , Package Orientation
Standard Pack Quantity	2500
Minimum Order Quantity (MOQ)	2500
Order Increment	2500
Estimated Lead Time (days)	42
HTS Code	8542.32.0040
ECCN	3A991

ECCN Suball	(B.2.A.)
-------------	----------

Quality and RoHS

Moisture Sensitivity Level (MSL)	3
Peak Reflow Temp. (°C)	260 (Cypress Reflow Profile)
RoHS Compliant	Y Print RoHS Certificate of Compliance
PB Free	Y
Lead/Ball Finish	Ni/Pd/Au
Marking	Cypress Marking Format

Package Material Declaration

[8L-SOIC PB-FREE PACKAGE MATERIAL DECLARATION DATASHEET](#) Last Update: 07/05/2012

IPC 1752 Material Declaration

[IPC-1752-2_V1.1_SOIC08_AMKOR](#) Last Update: 07/03/2012

[IPC-1752-2_V1.1_SOIC08_CML](#) Last Update: 07/05/2012

[IPC-1752-2_V1.1_SOIC08_OSE](#) Last Update: 07/04/2012

RoHS Analysis Certificates (CoA)

[PACKAGE ROHS ANALYSIS REPORT - SOIC \(SZ08,16,18,20,24\) USING MOLD COMPOUND MP8500, ADHESIVE QMI509, NIPDAU - CML ASSEMBLY](#) Last Update: 07/03/2012

[PACKAGE ROHS ANALYSIS REPORT - SOIC \(SZ08, 16, 18, 20, 24, 32\) SSOP \(SP16, 20, 28, 48\) USING MOLD](#)

[COMPOUND G600, ADHESIVE 8290, PURE SN - AMKOR PHILS. ASSEMBLY](#) Last Update: 07/04/2012

[PACKAGE ROHS ANALYSIS REPORT - SSOP \(SP 20,28,48,56\) SOIC \(SZ08,14,16\) USING MOLD COMPOUND CEL9220HF, ADHESIVE 4900G, NIPDAU - OSE TAIWAN ASSEMBLY](#) Last Update: 07/04/2012

Device Qualification Reports

 FIT/MTBF, ESD (HBM/CDM) and Latch-up data available in the Device Qualification Report. Please click [here](#).

Technical Documents

Application Notes (11)

[AN74875 - Designing with Serial I2C nvSRAM](#) Last Update: 06/05/2013

[AN87209 - An Overview of nvSRAM I2C I/O Specs Standardized by Cypress across I2C Modes](#) Last Update: 26/04/2013

[AN43593 - Storage Capacitor \(V_{CAP}\) Options for Cypress nvSRAM](#) Last Update: 21/03/2013

[AN43380 - HSR Operation in nvSRAMs](#) Last Update: 03/10/2012

[Show More](#)

Product Information Notice (PIN) (1)

[PIN135200](#) Last Update: 21/03/2013

Support and Community

[Cypress Developer Community](#)™

[Forums](#)

[Blogs](#)

[Support](#)

[Knowledge Base](#)

[Product Training](#)